**SDLS007** 

D2635, JANUARY 1981-REVISED MARCH 1988

- 8-Bit Parallel Storage Register Inputs ('LS597)
- Parallel 3-State I/O, Storage Register Inputs, Shift Register Outputs ('LS598)
- Shift Register has Direct Overriding Load and Clear
- Accurate Shift-Frequency . . . DC to 20 MHz

#### description

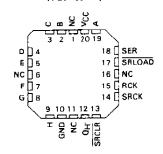
The 'LS597 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Both the storage register and shift register have positive-edge triggered clocks. The shift register also has direct load (from storage) and clear inputs.

The 'LS598 comes in a 20-pin package and has all the features of the 'LS597 plus 3-state I/O ports that provide parallel shift register outputs and also has multiplexed serial data inputs.

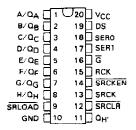
SN54LS597 . . . J OR W PACKAGE SN74LS597 . . . N PACKAGE (TOP VIEW)



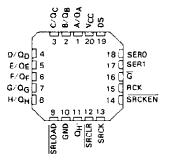
SN54LS597 . . . FK PACKAGE (TOP VIEW)



SN54LS598 . . . J OR W PACKAGE LS598 . . . DW OR N PACKAGE (TOP VIEW)

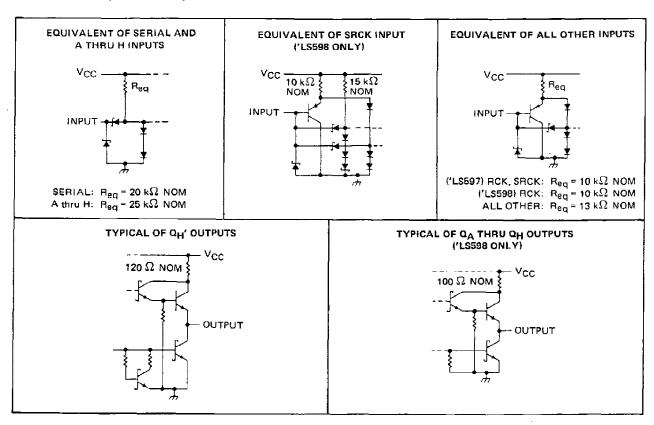


SN54LS598 . . . FK PACKAGE (TOP VIEW)

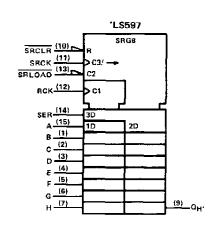


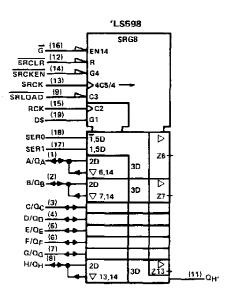
NC - No internal connection

#### schematics of inputs and outputs



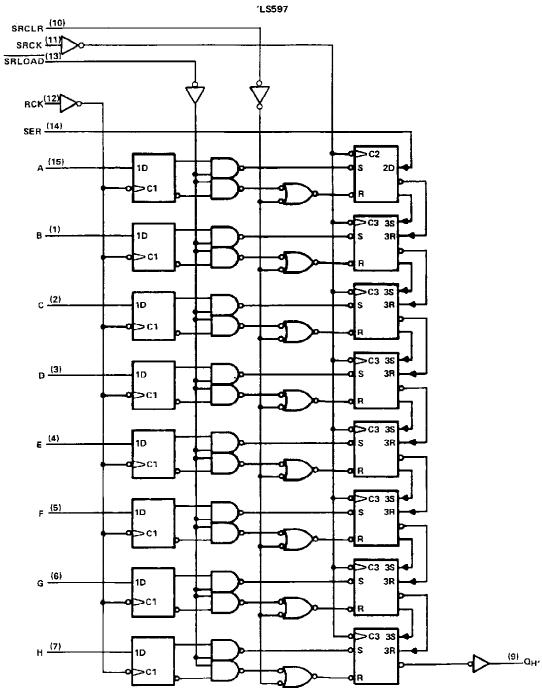
#### logic symbols †



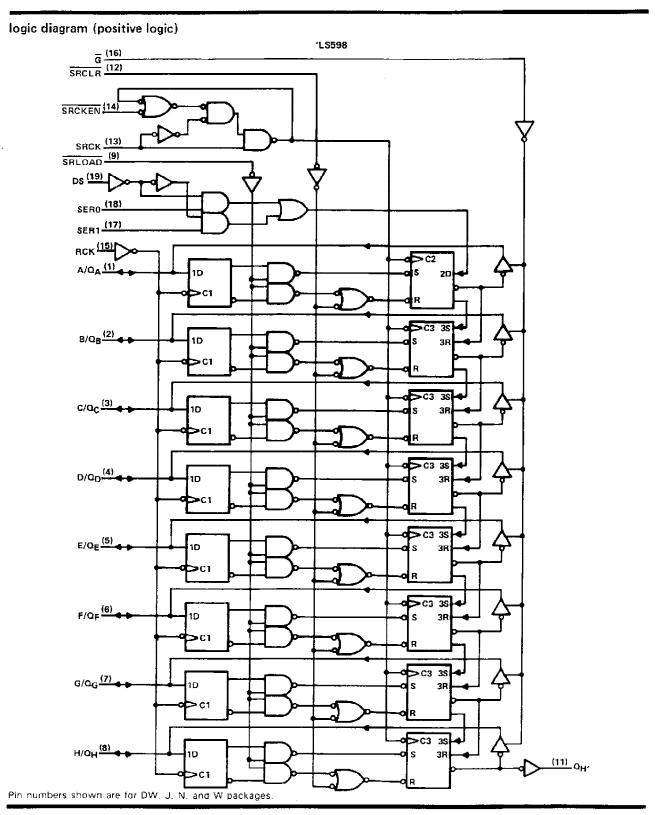


<sup>&</sup>lt;sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.

#### logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.



### 

NOTE 1: Voltage values are with respect to the network ground terminal,

#### recommended operating conditions

				•	SN54LS'				UNIT			
				1	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage							4.75	5	5.25	٧	
VIH	High-level input v	oltage			2			2			٧	
VIL	Low-level input vi	oltage					0.7			0.8	V	
	I Policia di Caracia		ΩH'		l		- 1			<b>– 1</b>	mΑ	
іон	High-level output	current	QA thru Q	, 'L\$598 only						- 2.6	1000	
			ΩH	Q <sub>H</sub> ,			8			16		
IOL	Low-level output	current	QA thru Q+	QA thru QH, 'L\$598 only			12			24	mA	
fsck	Shift clock freque	псу	y				20	0		20	MHz	
			SRCK	hīgh	15			15				
				low	35			35				
t <sub>w</sub>	Pulse duration		RCK	20			20			ns		
			SRCLR	20			20					
			SRLOAD	40			40					
		Data before F	e RCK1					20			]	
	-	DS before SR		SRCK † ('L\$598 anly)				30				
		SRCK EN ION	SRCKEN low before SRCK † ('LS598 only)					20				
t <sub>su</sub>	Setup time	SRCLR inact	ive before SRCk	C 1	25			25			⊓s	
		SRLOAD ina	SRLOAD inactive before SRCK †					30				
		RCK † before	RCK † before SRLOAD † (see Note 2)					40				
		SER before S	SER before SRCK t					20				
th	Hold time							0			ns	
TA	Operating free-air	- 55		125	0		70	°C				

NOTE 2: The RCK 1 before SRLOAD 1 setup time ensures the data saved by RCK 1 will also be loaded into the shift register.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN54LS	,	. :	SN74LS	,	UNIT		
PARAMETER		Т	MIN	TYP‡	MAX	MIN	TYP‡	MAX	CIVIT		
Vik		VCC = MIN,	I <sub>I</sub> = - 18 mA				- 1.5			- 1.5	٧
	T	VCC = MIN,	V= 2 V	I <sub>OH</sub> = - 1 mA	2.4	3.2					
∨он	'LS598 Q	ACC - MAX	VIH - Z V,	I <sub>OH</sub> = - 2.6 mA				2.4	3.1		V
	α <sub>H</sub> ′	VIL-WAX		i <sub>OH</sub> = - 1 mA	2.4	3.2		2.4	3.2		
	'LS598 Q			I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	
Vo∟	C3396 G	V <sub>CC</sub> = MIN,	$V_{1H} = 2 V$ ,	IOL = 24 mA					0.35	0.5	v
VOL	ΩH,	V <sub>IL</sub> ≃ MAX		IOL = 8 mA		0.25	0.4	ļ	0.25	0.4	,
	ЧН	3		IOL = 16 mA				L	0.35	0.5	
lozh	'L\$598 Q	V <sub>CC</sub> = MAX, V <sub>O</sub> = 2.7 V	V <sub>IH</sub> = 2 V,	V <sub>1L</sub> = MAX,			20			20	μA
lozt	'LS598 Q	V <sub>CC</sub> = MAX, V <sub>O</sub> = 0.4 V	V <sub>IH</sub> = 2 V,	VIL = MAX,			- 0.4			- 0.4	mА
	'LS598 Q		-	V <sub>1</sub> = 5.5 V			0.1			0.1	mA
11	Others	VCC = MAX		V <sub>1</sub> = 7 V			0.1			0,1	m <b>A</b>
ЧН	· · · · · · · · · · · · · · · · · · ·	VCC = MAX.	V <sub>I</sub> = 2.7 V	•			20			20	μА
	'L\$598 SRCK				Ì		- 0.8			- 0.8	
11L	SER, A Thru H	VCC = MAX,	V <sub>I</sub> = 0.4 V				- 0.4			- 0.4	mA
	Others						- 0.2			- 0.2	
los§	'LS598 Q	V <sub>CC</sub> = MAX,	Vo = 0 V		- 30		- 130	- 30		- 130	m.A.
אצטי	ΩH'	1 100 1100	•0 ••	v0-0 v			<b>–</b> 100	- 20		<u> </u>	
	'LS597 ICCH				<u> </u>	35	53		35	53	
	lccr	V <sub>CC</sub> = MAX,				35	53		35	53	
lcc	Іссн	All possible inc	outs grounded,			45	68		45	68	mΑ
	'LS598 ICCL	All outputs op	en			54	80		54	80	
	CCZ					56	85		56	85	

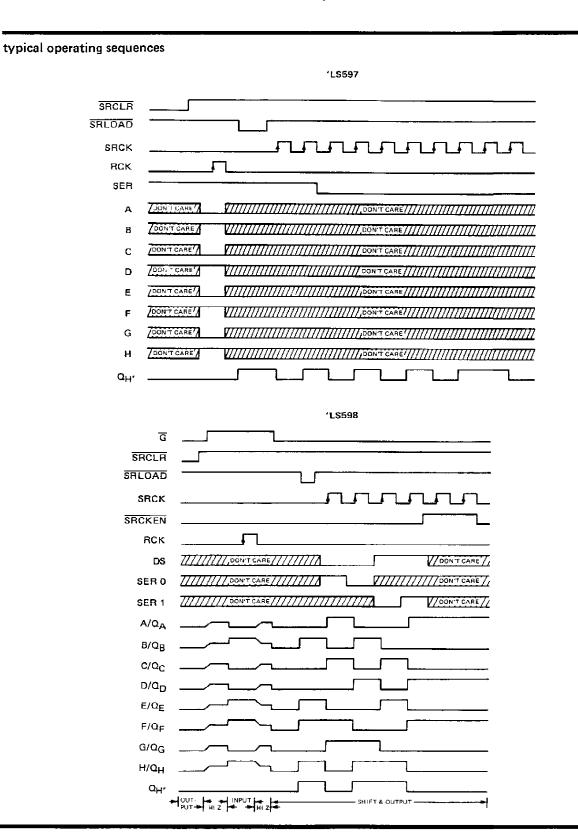
<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $<sup>\</sup>ddagger$  All typical values are at V<sub>CC</sub>  $\pm$  5 V, T<sub>A</sub>  $\pm$  25°C §Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics,  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25 \,^{\circ}\text{C}$ , (see note 3)

	FROM	то			<b>1</b> S597	,		UNIT			
PARAMETER	(INPUT)	(OUTPUT)	TEST CON	MIN	TYP	MAX	MIN	TYP	MAX	UNII	
fmax	SRCK	a	$R_L = 667 \Omega$ ,	CL = 45 pF	20	35		20	35		MHz
f <sub>max</sub>	SRCK	QH'	$R_L = 1 k\Omega$	C <sub>L</sub> = 30 pF	20	35					MHz
tPLH	SRCK†	ΩH'				15	23	l	11	17	ns
tPHL	SPCK1	QH'	D 11.0	C <sub>L</sub> = 30 pF		20	30		15	23	กร
†PLH	SRLOAD↓	ΩH,	H <sub>L</sub> = 1 KW,			38	57		28	42	กร
<sup>T</sup> PHL	SRLOAD↓	α <sub>H</sub> '				29	44		20	30	ns
t <sub>PHL</sub>	SRCLR	α <sub>H</sub> '				24	36		18	27	ns
<sup>t</sup> PLH	RCK1	α <sub>H</sub> ′	$R_L = 1 \text{ k}\Omega.$	Ct = 30 pF		41	60		32	48	ns
<sup>†</sup> PHL	RCK1	αH.	SRLOAD = L			32	48	ĺ .	24	36	nş
<sup>†</sup> PLH	SRCKt	a			[			1	12	18	ns
<sup>†</sup> PHL	SRCK1	α	j						19	28	ПБ
<sup>t</sup> PLH	SRLOAD↓	α		C <sub>1</sub> = 45 pF		-			32	48	ns
<sup>†</sup> PHL	SRLOAD↓	α	RL = 667 Ω.						27	40	пз
TPHL	SRCLR+	α	_						25	38	ns
<sup>†</sup> PZH	G↓	a							26	31	ns
t PZL	G∔	Q							29	43	ns
t <sub>PHZ</sub>	Gt	Q	D 667.6	C 55					25	38	ns
tPLZ	Gt	Q	$\mathbf{A_L} = 667 \Omega,$	CL = b pF					20	30	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





www.ti.com 16-Jun-2023

### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-89444012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 89444012A SNJ54LS 597FK	Samples
5962-8944401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401EA SNJ54LS597J	Samples
5962-8944401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401EA SNJ54LS597J	Samples
5962-8944401FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401FA SNJ54LS597W	Samples
5962-8944401FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401FA SNJ54LS597W	Samples
SN74LS597D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS597	Samples
SN74LS597D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS597	Samples
SN74LS597N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS597N	Samples
SN74LS597N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS597N	Samples
SN74LS598N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS598N	Samples
SN74LS598N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS598N	Samples
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 89444012A SNJ54LS 597FK	Samples
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 89444012A SNJ54LS 597FK	Samples
SNJ54LS597J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401EA SNJ54LS597J	Samples
SNJ54LS597J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401EA SNJ54LS597J	Samples

### PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS597W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401FA SNJ54LS597W	Samples
SNJ54LS597W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8944401FA SNJ54LS597W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54LS597, SN74LS597:

Military: SN54LS597

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-89444012A	FK	LCCC	20	1	506.98	12.06	2030	NA
5962-8944401FA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS597D	D	SOIC	16	40	507	8	3940	4.32
SN74LS597N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS597N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS598N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54LS597FK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS597W	W	CFP	16	1	506.98	26.16	6220	NA

## W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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